



SOT889-1

plastic rectangular-DIL-bent-SIL (reverse bent) power package; 23 leads (row spacing 2.54 mm)

8 February 2016

Package information

1. Package summary

Terminal position code	Z (zig-zag)
Package type descriptive code	RDBS23P
Package type industry code	RDBS23P
Package style descriptive code	RDBS (right-angle DIL-bent-SIL)
Package style suffix code	P (power)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	24-3-2005

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		29.9	-	30.2	30.4	mm
E	package width		11.8	-	12	12.2	mm
A ₂	package height		4.3	-	4.45	4.6	mm
n ₂	actual quantity of termination		-	-	23	-	



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2. Package outline

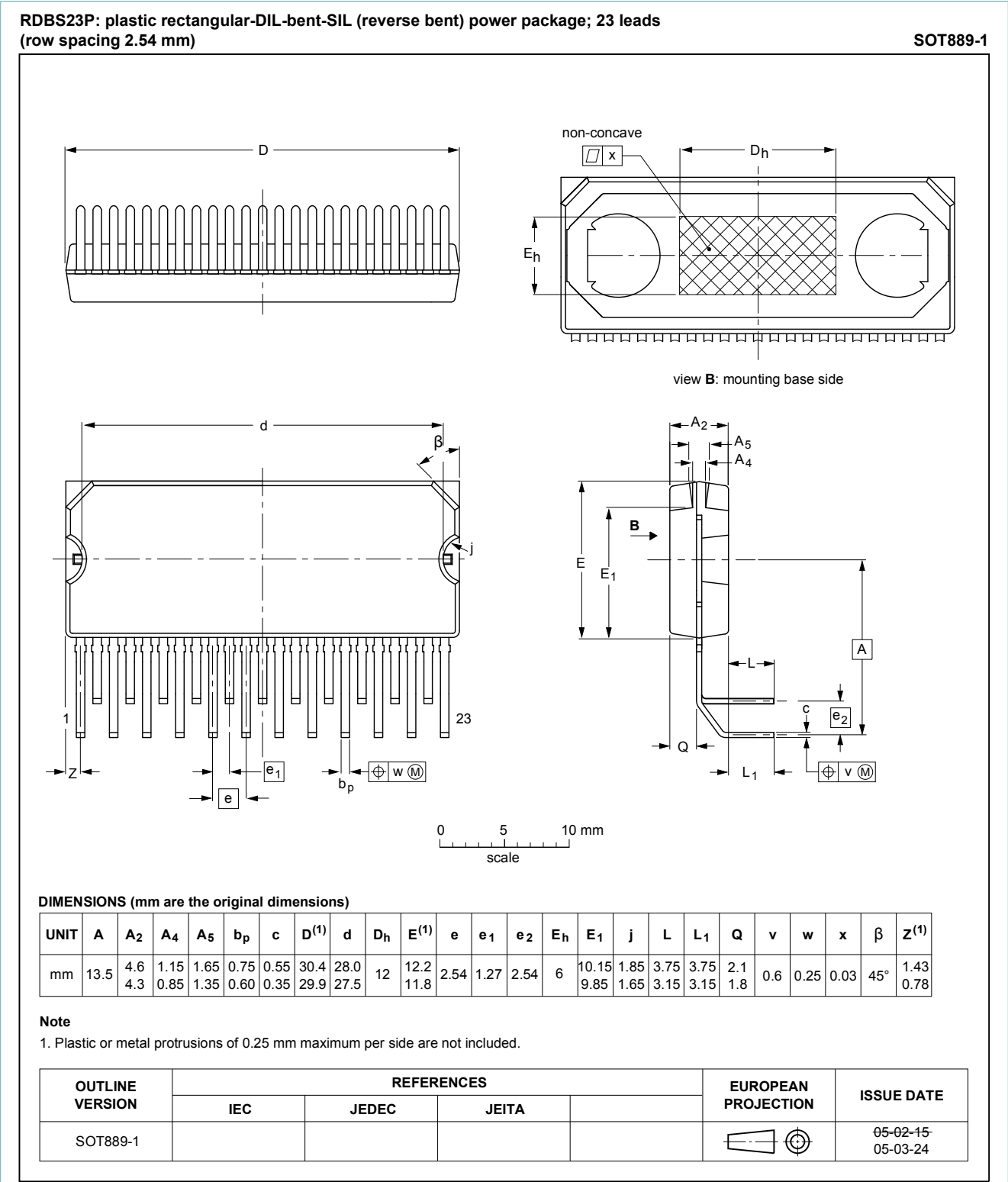


Fig. 1. Package outline RDBS23P (SOT889-1)

3. Legal information

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